

Abstract

This is a semiconductor apparatus capable of realizing a sharing of parts without introducing enlargement of the apparatus and deterioration in reliability of the wire bonding in case of responding to various electronic circuits. It is a semiconductor laser apparatus configured to include a housing (1) in which device mounting portions (1A), (1B) are respectively formed on both one surface side and the other surface side thereof; a semiconductor laser device (1) mounted in the device mounting portion (1A) on one surface side of this housing; a photo-diode (11) mounted in the device mounting portion (1B) on the other surface side of the housing; and a plurality of leads (3), (4), (5), and (6) connected through wires (8) to either the semiconductor laser device (7) or the photo-diode (11), wherein the pad portions (5B) of the leads (5) are exposed to the device mounting portions (1A), (1B) in the position relation alternate with each other on the one surface side and the other surface side of the housing (1), so that the wire bonding to the pads (5B) of the leads (5) is properly performed from either one surface side or the other surface side of the housing (1) by setting this exposed portion as the connection portion of the wire bonding.